2SC2309

Silicon NPN Epitaxial

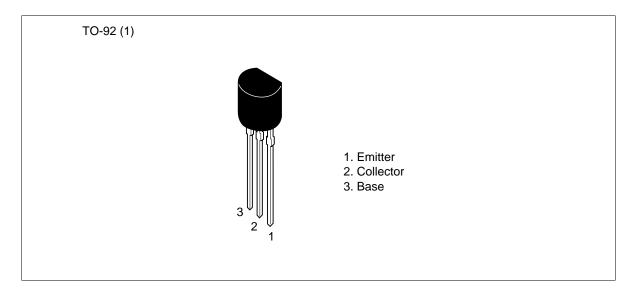
HITACHI

ADE-208-1061 (Z) 1st. Edition Mar. 2001

Application

Low frequency amplifier

Outline





2SC2309

Absolute Maximum Ratings $(Ta = 25^{\circ}C)$

| Item | Symbol | Ratings | Unit |
|------------------------------|------------------|-------------|------|
| Collector to base voltage | V_{CBO} | 55 | V |
| Collector to emitter voltage | V _{CEO} | 50 | V |
| Emitter to base voltage | V_{EBO} | 5 | V |
| Collector current | I _c | 100 | mA |
| Collector power dissipation | P _c | 200 | mW |
| Junction temperature | Tj | 150 | °C |
| Storage temperature | Tstg | -55 to +150 | °C |

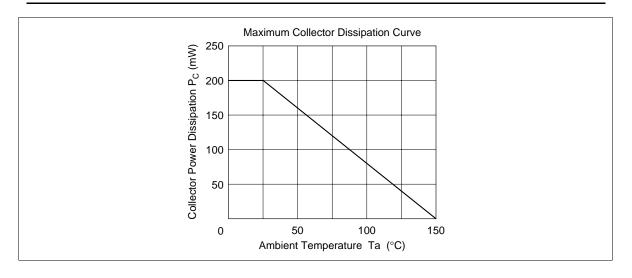
Electrical Characteristics ($Ta = 25^{\circ}C$)

| Item | Symbol | Min | Тур | Max | Unit | Test conditions |
|---|----------------------|-----|-----|------|------|---|
| Collector to base breakdown voltage | $V_{(BR)CBO}$ | 55 | _ | _ | V | $I_{c} = 10 \ \mu A, \ I_{E} = 0$ |
| Collector to emitter breakdown voltage | $V_{(BR)CEO}$ | 50 | _ | _ | V | I_{C} = 1 mA, R_{BE} = ∞ |
| Emitter to base breakdown voltage | $V_{(BR)EBO}$ | 5 | _ | _ | V | $I_{E} = 10 \ \mu A, \ I_{C} = 0$ |
| Collector cutoff current | I _{CBO} | _ | _ | 0.5 | μΑ | V _{CB} = 18 V, I _E = 0 |
| Emitter cutoff current | I _{EBO} | _ | _ | 0.5 | μΑ | $V_{EB} = 2 \text{ V}, I_{C} = 0$ |
| DC current transfer ratio | h _{FE} *1 | 250 | _ | 1200 | | $V_{CE} = 12 \text{ V}, I_{C} = 2 \text{ mA}$ |
| Base to emitter voltage | V _{BE} | _ | _ | 0.75 | V | V _{CE} = 12 V, I _C = 2 mA |
| Collector to emitter saturation voltage | $V_{\text{CE(sat)}}$ | _ | _ | 0.2 | V | $I_C = 10 \text{ mA}, I_B = 1 \text{ mA}$ |
| Gain bandwidth product | f _T | _ | 230 | _ | MHz | $V_{CE} = 12 \text{ V}, I_{C} = 2 \text{ mA}$ |
| Collector output capacitance | Cob | _ | 1.8 | 3.5 | pF | $V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$ |

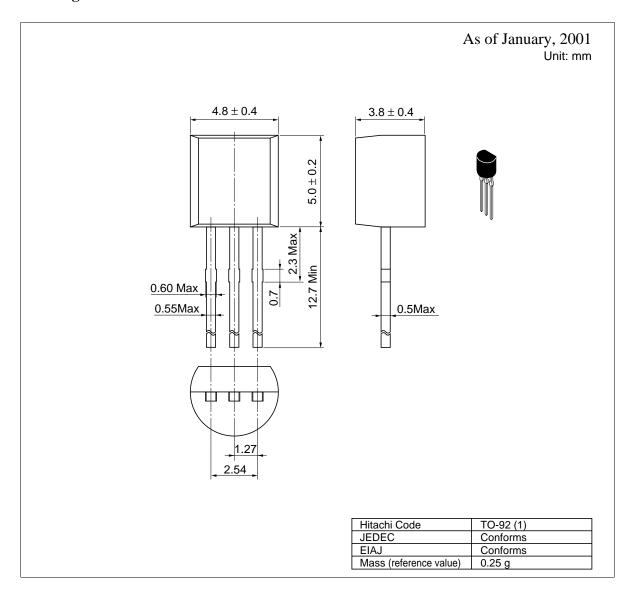
Note: 1. The 2SC2309 is grouped by $h_{\rm FE}$ as follows.

| D | E | F |
|------------|------------|-------------|
| 250 to 500 | 400 to 800 | 600 to 1200 |

See characteristic curves of 2SC1345.



Package Dimensions



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